

CLAIMS

What is claimed is:

5/29/17
BB

1. A method of fabricating an integrated circuit package, the method comprising:
providing a semiconductor die having a plurality of conductive pads;
forming at least two conductors, each conductor of the at least two conductors having a first end and a second end and a generally arcuate-shaped portion between the first and second ends, at least a portion of each generally arcuate-shaped portion exhibiting a constant radius;
configuring and positioning the at least two conductors such that line spacing between the generally arcuate-shaped portion of each of the at least two conductors is constant;
electrically coupling the first ends of each of the at least two conductors with at least one of the plurality of conductive pads; and
encapsulating the semiconductor die and at least a portion of the at least two conductors with an insulating material.

2. The method according to claim 1, wherein the forming at least two conductors further comprises forming a first conductor to exhibit a first arc length through its generally arcuate shaped portion and forming a second conductor to exhibit a second arc length through its generally arcuate shaped portion wherein the first arc length is different than the second arc length.

3. The method according to claim 1, wherein the forming at least two conductors further comprises forming each generally arcuate shaped portion of each of the at least two conductors to exhibit a different arc length than any other generally arcuate-shaped portion of any other conductor of the at least two conductors.

4. The method according to claim 1, wherein the forming at least two conductors includes forming the generally arcuate-shaped portion of at least one of the at least two conductors to include a plurality of segments including at least one straight segment and at least one generally arcuate segment.

5. The method according to claim 4, wherein the plurality of segments includes at least three segments.

6. The method according to claim 4, further comprising defining at least one segment of the plurality of segments to exhibit a different length than at least one other segment of the plurality of segments.

7. The method according to claim 1, wherein the forming at least two conductors includes forming at least one conductor of the at least two conductors such that the generally arcuate-shaped portion is a substantial portion of the at least one conductor.

8. The method according to claim 1, wherein the forming at least two conductors includes forming at least one conductor of the at least two conductors such that the generally arcuate-shaped portion exhibits a constant radius throughout an entire arc length thereof.

9. The method according to claim 1, further comprising configuring and positioning the at least two conductors such that line spacing between at least two conductors is constant from the respective first ends to the respective second ends of the at least two conductors.

10. The method according to claim 1, further comprising configuring the first and second ends of each of the at least two conductors to be positioned at orientations of substantially 90° relative to each other.

11. The method according to claim 1, further comprising configuring the generally arcuate-shaped portion of each of the at least two conductors to exhibit a substantially 90° arc.

12. A method of forming a lead frame, the method comprising:
providing a plurality of conductors each having a first end configured for attachment to a semiconductor die and a second end configured for attachment to an electronic system;
defining at least a portion of each conductor of the plurality to exhibit a generally arcuate shape having a constant radius;
defining the generally arcuate shape of each conductor of the plurality to exhibit a different length than the generally arcuate shape of any other conductor of the plurality;
positioning each conductor of the plurality adjacent at least one other conductor of the plurality and so as to define substantially constant spacing between the generally arcuate shapes of adjacent conductors of the plurality.

13. The method according to claim 12, further comprising locating the first and second ends of each conductor approximately 90° relative to each other.

14. The method according to claim 12, further comprising forming the generally arcuate shape of each conductor of the plurality to exhibit a substantially 90° arc.

15. The method according to claim 12, further comprising providing a second plurality of conductors and configuring each of the second plurality of conductors for attachment with a semiconductor device.